



**IPC-6904**

# **Qualification and Performance Specification for Printed Electronics on Rigid Substrates**

If a conflict occurs between the English language and translated versions of this document, the English version will take precedence.

Developed by the Printed Electronics on Rigid Substrates Performance Specification Task Group (D-64b) of the Printed Electronics Committee (D-60) of IPC

Users of this publication are encouraged to participate in the development of future revisions.

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# Table of Contents

<b>1</b>	<b>SCOPE</b> .....	<b>1</b>			
1.1	Purpose.....	1	3.3.1.1	Printed Conductor Pattern.....	6
1.2	Classification.....	1	3.3.1.2	Printed Conductor Spacing .....	6
1.3	Measurement Units .....	1	3.3.1.3	Printed Conductor Surface Mount Lands .....	6
1.4	Definition of Requirements .....	1	3.3.1.4	Separation Between Printed Elements and Printed Elements and Substrate .....	6
1.5	Process Control Requirements .....	1	3.3.1.5	Foreign Object Debris (FOD).....	6
1.6	Order of Precedence.....	2	3.3.1.6	Surface Defects .....	6
1.6.1	Conflict.....	2	3.3.1.7	Discoloration .....	7
1.6.2	Clause References.....	2	3.3.1.8	Mechanical Damage to Substrate.....	7
1.6.3	Appendices .....	2	3.3.2	Registration .....	7
1.7	Use of “Lead” .....	2	3.3.2.1	Horizontal Registration Between Printed Features .....	7
1.8	Abbreviations and Acronyms .....	2	3.3.2.2	Minimum Overlap of Conductors .....	7
1.9	Terms and Definitions .....	2	3.3.2.3	Overlap of Conductors for Electromigration Prevention .....	7
1.9.1	Via .....	2	3.3.2.4	Trimmed-Edge Registration .....	7
1.9.2	Foreign Object Debris (FOD) .....	2	3.3.3	Dielectric Wetting .....	7
1.10	Printed Electronics Types.....	2	3.3.4	Adhesion .....	7
1.11	Standard Printed Electronic Design .....	3	3.3.5	Marking.....	7
1.12	Selection for Procurement.....	3	3.3.6	Defects in Printed Materials.....	8
1.12.1	Production Master and Database .....	3	3.3.6.1	Variations in Conductor Height and Width ...	8
1.12.2	Deviations and Waivers.....	3	3.3.6.2	Variations in Dielectric Height and Width ....	8
1.12.3	Selection (Default) .....	4	3.3.6.3	Voids in Printed Dielectric Between Conductors .....	8
<b>2</b>	<b>APPLICABLE DOCUMENTS</b> .....	<b>4</b>	3.3.6.4	Voids in Printed Conductive Planes .....	8
2.1	IPC.....	4	3.3.6.4.1	Voids in Printed Electromigration-Resistant Conductive Layers .....	8
2.2	American Society for Quality .....	5	3.3.6.5	Filled Vias .....	9
2.3	ASTM International .....	5	3.3.7	Workmanship .....	9
2.4	JEDEC.....	5	3.4	Dimensional Requirements .....	9
<b>3</b>	<b>REQUIREMENTS</b> .....	<b>5</b>	3.4.1	Pattern Feature Accuracy .....	9
3.1	General .....	5	3.4.2	Bow and Twist .....	9
3.2	Materials.....	5	3.5	Printed Materials Mechanical Requirements	9
3.2.1	Rigid Base Materials .....	5	3.6	Nonprinted Solderable Surfaces.....	9
3.2.2	External Bonding Materials .....	5	3.7	Structural Integrity .....	9
3.2.3	Printed Dielectric Materials. ....	5	3.7.1	Requirements for Coupons or Rigid Printed Electronic Devices after Thermal Stressing.	10
3.2.4	Printed Conductive Materials .....	5	3.7.1.1	Separation, Cracking and Voids .....	10
3.2.5	Printed Passive Materials .....	6	3.7.1.2	Printed Element Height.....	10
3.2.6	Marking Inks.....	6	3.7.1.3	Overlap of Filled Holes.....	10
3.2.7	Final Finishes, Coatings and Platings (Metallic and Nonmetallic) .....	6			
3.3	Visual Examination .....	6			
3.3.1	Visual Imperfections .....	6			

3.7.1.4	Conductive Hole Fill.....	10	4.3.2	Quality Conformance.....	14	
3.7.1.5	Dielectric Spacing.....	10	4.3.2.1	Inspection Lot .....	17	
3.7.1.6	Discoloration .....	10	4.3.2.2	Traceability.....	17	
3.7.1.7	Adhesion .....	10	4.3.2.3	Acceptance .....	17	
3.8	Electrical Requirements .....	10	4.3.2.4	Rejected Lots.....	17	
3.8.1	Dielectric Withstanding Voltage.....	10	4.4	Reliability Test and Evaluation .....	17	
3.8.2	Electrical Continuity and Isolation Resistance.....	11	4.4.1	Noncompliance .....	17	
3.8.3	Moisture and Insulation Resistance (MIR) .....	11	4.5	Qualification.....	17	
3.8.3.1	Dielectric Withstanding Voltage after MIR .....	12	4.5.1	Sample Test Coupons .....	17	
3.9	Special Requirements .....	12	4.6	Acceptance Testing and Frequency.....	17	
3.9.1	Outgassing .....	12	4.6.1	C=0 Zero Acceptance Number Sampling Plan .....	18	
3.9.2	Fungus Resistance .....	12	4.6.2	Additional Test Coupons for Suspected Isolated Defects.....	18	
3.9.3	Vibration.....	12	<b>5</b>	<b>NOTES.....</b>	<b>18</b>	
3.9.4	Mechanical Shock .....	12	5.1	Ordering Data .....	18	
3.9.5	Impedance Testing.....	12	<b>APPENDIX A.....</b>	<b>19</b>		
3.9.6	Coefficient of Thermal Expansion (CTE) .....	12				
3.9.7	Thermal Shock .....	12				
3.9.8	Surface Insulation Resistance (As Received).....	12				
3.9.9	Ultraviolet (UV) Resistance .....	13				
3.9.10	Material Removal or Replacement.....	13				
3.9.11	Simulation for Component Assembly and Rework.....	13				
3.9.12	Adhesion .....	13				
3.9.13	Destructive Physical Analysis (DPA).....	13				
3.9.14	Solderability .....	13				
3.9.15	Abrasion Resistance.....	13				
3.9.16	Accelerated Aging.....	13				
3.9.17	Silver Migration .....	13				
3.9.18	Current Carrying Capacity .....	13				
3.9.19	Repair .....	13				
3.9.20	Rework.....	13				
<b>4</b>	<b>QUALITY ASSURANCE PROVISIONS.....</b>	<b>13</b>				
4.1	Responsibility for Inspection .....	13				
4.1.1	Test Equipment and Inspection Facilities .....	13				
4.1.2	Contract Services .....	13				
4.2	Materials Inspection .....	13				
4.3	Quality Conformance Inspection .....	14				
4.3.1	Inspection of Product for Delivery.....	14				
				<b>Figures</b>		
				Figure 1-1	Example of Printed Electronic Using Every Standard Printed Electronic Design (SPED) Type in One Device .....	2
				Figure 3-1	Surface Mount Land Defects .....	7
				Figure 3-2	Foreign Object Debris (FOD) .....	7
				Figure 3-3	Conductor Overlap .....	8
				Figure 3-4	Variation in Conductor Height and Width .....	8
				Figure 3-5	Voids in Printed Dielectric Between Printed Conductors .....	9
				Figure 3-6	Conductive Hole Fill Class 2 and 3 .....	10
				Figure 3-7	Conductive Hole Fill Class 1 .....	10
				Figure 3-8	Resistive Continuity Test Illustrations (Network Resistance) .....	11
					<b>Tables</b>	
				Table 1-1	Default Requirements .....	4
				Table 3-1	Dielectric Withstanding Test Voltages .....	11
				Table 3-2	Insulation Resistance .....	11
				Table 3-3	Surface Insulation Resistance .....	12
				Table 4-1	Qualification Testing and Acceptance Testing Frequency .....	14
				Table 4-2	C=0 Sampling Plan Per Lot Size .....	17